

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
CTL MEDICAL CORPORATION D/B/A CTL AMEDICA	01/01/2023
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	CTL BIOTEC, CORPORATION
<b>Street Address:</b>	SEONGSEO-RO 329
<b>Internal Address:</b>	SUITE 410, DALSEO-GU
<b>City:</b>	DAEGU
<b>State/Country:</b>	KOREA, REPUBLIC OF
<b>Postal Code:</b>	42703
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17559565
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(856)206-5383
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>NAME OF SUBMITTER:</b>	MARIAH WY SOCKI
<b>SIGNATURE:</b>	/Mariah Wysocki/
<b>DATE SIGNED:</b>	04/03/2023
<b>Total Attachments: 2</b>	
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source=Assignment#page2.tif	

**CONFIRMATORY ASSIGNMENT AGREEMENT**

**THIS ASSIGNMENT** is made by CTL MEDICAL CORPORATION D/B/A CTL AMEDICA, a Delaware corporation having an address of 4550 Excel Parkway #300, Addison, TX 75001 ("Assignor"), and CTL BIOTEC, CORPORATION., a South Korea corporation having an address of Seongseo-ro 329, Suite 410, Dalseo-gu, Daegu, South Korea 42703 ("Assignee");

**WHEREAS**, Assignor is the owner of the entire right, title and interest in the U.S. Patents/Applications (herein after referred to as "Patent Properties") set forth on Exhibit A; and

**WHEREAS**, Assignee desires to confirm acquisition of the full and exclusive right, title and interest to the Patent Properties.

**NOW, THEREFORE**, for good and sufficient consideration, the receipt of which is hereby acknowledged, Assignor hereby acknowledges and confirms that Assignor has sold, assigned, conveyed and transferred to Assignee the full and exclusive right, title and interest in the United States of America and throughout the world to said Patent Properties, and any renewals, divisionals, extensions, continuations, substitutes, re-examinations, reissues, supplemental examinations, post grant reviews, inter partes reviews, foreign counter-parts, and/or extensions and all applications to which the Patent Properties claims or may be entitled to claim priority, as fully and entirely as the same would have been held had this assignment and sale not been made, and including but not limited to the right to sue for, and recover for any and all past infringements of the Patent Properties, as set forth in the Intellectual Property Purchase Agreement dated January 1, 2023, and Assignee hereby acknowledges receipt of the entire right, title and interest in and to the Patent Properties.

**AND** for the same consideration, Assignor hereby covenants to and agrees with Assignee, its successors, legal representatives and assigns, that Assignor will sign all papers and documents, make all lawful declarations and do all acts necessary or required to be done for the procurement, maintenance, enforcement and defense of any Patent Properties for said inventions, whenever counsel of Assignee, or counsel of its successors, legal representatives and assigns, shall advise including but not limited to interference proceedings, any division, continuation or continuation-in-part of any application for Patent Properties, or any reissue, reexamination inter partes review, post grant review, or extension of any Patent Properties, to be obtained thereon.

**CTL BIOTEC, CORPORATION**  
a South Korea corporation

By: \_\_\_\_\_

Name: Haejun Jeong

Title: Vice President

**CTL MEDICAL CORPORATION**  
D/B/A CTL AMEDICA

By: \_\_\_\_\_

Name: Daniel Chon

Title: CEO

## **EXHIBIT A**

### **Patent Properties**

<b><u>Patent/Patent Application</u></b>	<b><u>Description</u></b>
U.S. Patent No. 11,291,559 (U.S. Patent Application No. 17/194,034)	EXPANDABLE INTERBODY FUSION DEVICE AND METHOD OF MANUFACTURING THE SAME
International Patent Application No. PCT/US2022/017542	EXPANDABLE INTERBODY FUSION DEVICE AND METHOD OF MANUFACTURING THE SAME
U.S. Patent Application No. 17/684,079	EXPANDABLE INTERBODY FUSION DEVICE
Korean Patent Application No. 10-2022-7010411	VERTICAL EXPANSION CAGE
U.S. Patent Application No. 17/559,565	EXPANDABLE BI-DIMENSIONAL INTERBODY AND METHOD OF MANUFACTURING THE SAME